

In the Claims

Please amend claims 13-15, 17-18, 35-42, and 44-47 as follows below.

Please add new claims 50-55 as follows below.

Please accept a marked up version of the entire set of pending claims including the amendments made herein.

Marked Up Version of Pending Claims

1 1-12. (Cancelled)

1 13. (Currently Amended) A method for assembling an electronic
2 package, comprising:

3 forming a housing which has a bond pad located on a ~~first~~
4 top surface of a bond shelf, the bond shelf having a ~~second~~ an
5 inner side surface along a thickness of the bond shelf;

6 forming a conductive strip lengthwise along the inner side
7 ~~second~~ surface of the bond shelf; and

8 removing a portion of the conductive strip along the ~~second~~
9 inner side surface of the bond shelf to form a pair of separate
10 conductive strips lengthwise along the ~~second~~ inner side surface
11 of the bond shelf.

1 14. (Currently Amended) The method as recited in claim 13,
2 wherein

3 the conductive strip is formed by plating a conductive
4 material onto the ~~second~~ inner side surface of the bond shelf.

1 15. (Currently Amended) The method as recited in claim 13,
2 wherein

3 the portion of the conductive strip is removed by
4 drilling a portion of the ~~second~~ inner side surface of
5 the bond shelf including the conductive strip.

1 16. (Previously Presented) The method as recited in claim 13,
2 further comprising:

3 mounting an integrated circuit to the housing and
4 connecting the integrated circuit to the bond pad.

1 17. (Currently Amended) The method as recited in claim 14,
2 wherein

3 the portion of the conductive strip is removed by
4 etching away a portion of the conductive material on
5 the ~~second~~ inner side surface of the bond shelf.

1 18. (Currently Amended) The method as recited in claim 13,
2 wherein

3 the conductive strip is formed along the second surface of
4 the bond shelf by

5 masking ~~all~~ surfaces of the bond shelf except for
6 portions of the bond shelf to be plated, the ~~second~~ inner
7 side surface of the bond shelf being unmasked, and
8 plating a conductive material onto the ~~second~~ inner
9 side surface of the bond shelf.

1 19. (Previously Presented) The method as recited in claim 18,
2 wherein
3 the conductive material is copper, and
4 the conductive strip is further formed by plating gold
5 onto the copper.

1 20. (Previously Presented) The method as recited in claim 19,
2 wherein
3 the portion of the conductive strip is removed by
4 drilling a portion of the bond shelf.

1 21-34. (Cancelled)

1 35. (Withdrawn - Currently Amended) The method as recited in
2 claim 13, wherein
3 the forming of the conductive strip further includes
4 forming a portion of the conductive strip around onto
5 the ~~first~~ top surface of the bond shelf to couple to the

6 bond pad on the ~~first~~ top surface of the bond shelf.

1 36. (Withdrawn - Currently Amended) The method as recited in
2 claim 35, wherein

3 the portion of the conductive strip around on the
4 ~~first~~ top surface of the bond shelf to further anchor the
5 conductive strip to the housing.

1 37. (Withdrawn - Currently Amended) The method as recited in
2 claim 13, wherein

6 3 the forming of the conductive strip further includes
4 forming a portion of the conductive strip around onto
5 the ~~first~~ top surface of the bond shelf to form another
6 bond pad on the ~~first~~ top surface of the bond shelf.

1 38. (Withdrawn - Currently Amended) The method as recited in
2 claim 37, wherein

3 the portion of the conductive strip around on the
4 ~~first~~ top surface of the bond shelf to further anchor the
5 conductive strip to the housing.

1 39. (Currently Amended) A method for assembling an electronic
2 package, comprising:

3 forming a housing which has a bond pad located on a top
4 surface of a bond shelf, the bond shelf having an inside ~~a side~~
5 surface along an edge of the bond shelf;

6 plating a conductive material along the inside ~~side~~ surface
7 of the bond shelf; and

8 removing a portion of the conductive material along the
9 inside ~~side~~ surface of the bond shelf to form a pair of separate
10 conductive strips along the inside ~~side~~ surface of the bond
11 shelf.

6
1 40. (Currently Amended) The method of claim 39, wherein
2 the portion of the conductive material is removed by
3 drilling into the edge of the bond shelf including the
4 conductive material and the inside ~~side~~ surface.

1 41. (Currently Amended) The method of claim 39, wherein
2 the portion of the conductive material is removed by
3 etching away a portion of the conductive material from
4 the inside ~~side~~ surface of the bond shelf.

1 42. (Currently Amended) The method of claim 39, wherein,
2 the plating of the conductive material onto the inside ~~side~~
3 surface of the bond shelf includes
4 masking surfaces of the housing that are not to be

5 plated and

6 leaving surfaces of the housing unmasked that are to
7 be plated, including the inside ~~side~~ surface of the bond
8 shelf that is to be plated.

1 43. (Previously Presented) The method of claim 42, wherein
2 the plating of the conductive material further includes
3 plating copper onto the unmasked surfaces of the
4 housing, and
5 plating gold onto the copper.

6
1 44. (Currently Amended) The method of claim ~~39~~ 43, wherein
2 the portion of the conductive material is removed by
3 drilling into the edge of the bond shelf including the
4 conductive material and the inside ~~side~~ surface.

1 45. (Withdrawn - Currently Amended) The method of claim 39,
2 wherein
3 the plating of the conductive material further includes
4 plating a portion of the conductive material from the
5 inside ~~side~~ surface around onto the top surface of the bond
6 shelf to couple to the bond pad on the top surface of the
7 bond shelf.

1 46. (Withdrawn - Currently Amended) The method of claim 45,
2 wherein

3 the portion of the conductive material plated around
4 onto the inside ~~side~~ surface of the bond shelf to further
5 anchor the conductive material to the housing.

1 47. (Withdrawn - Currently Amended) The method of claim 39,
2 wherein

3 the plating of the conductive material further includes
4 plating a portion of the conductive material from the
5 inside ~~side~~ surface around onto the top surface of the bond
6 shelf to form another bond pad on the top surface of the
7 bond shelf.

1 48. (Withdrawn) The method of claim 47, wherein

2 the portion of the conductive material plated around
3 onto the top surface of the bond shelf to further anchor
4 the conductive material to the housing.

1 49. (Withdrawn) The method of claim 39, further comprising:
2 mounting an integrated circuit to the housing and
3 connecting the integrated circuit to the bond pad.

1 50. (New) A method for assembling an electronic package,
2 comprising:
3 forming a housing which has a plurality of bond pads
4 located on a top surface of a bond shelf, the bond shelf forming
5 a rectangular cavity wall along an inner side of the bond shelf;
6 forming a conductive strip lengthwise along the rectangular
7 cavity wall of the bond shelf; and
8 removing portions of the conductive strip along the
9 rectangular cavity wall of the bond shelf to form a plurality of
10 separate conductive strips along the rectangular cavity wall of
11 the bond shelf.

1 51. (New) The method as recited in claim 50, wherein
2 the conductive strip is formed by plating a conductive
3 material onto the rectangular cavity wall of the bond shelf.

1 52. (New) The method as recited in claim 50, wherein
2 portions of the conductive strip are removed by
3 drilling a portion of the rectangular cavity wall of
4 the bond shelf including the conductive strip.

1 53. (New) The method as recited in claim 50, further
2 comprising:

3 mounting an integrated circuit to the housing and
4 connecting the integrated circuit to at least one of the
5 plurality of bond pads.

1 54. (New) The method as recited in claim 50, wherein
2 portions of the conductive strip are removed by
3 etching away portions of the conductive material on
4 the rectangular cavity wall of the bond shelf.

6
1 55. (New) The method as recited in claim 50, wherein
2 the conductive strip is formed along the rectangular cavity
3 wall of the bond shelf by
4 masking surfaces of the bond shelf except for portions
5 of the bond shelf to be plated, the rectangular cavity wall
6 of the bond shelf being unmasked, and
7 plating a conductive material onto the rectangular
8 cavity wall of the bond shelf.

REMARKS

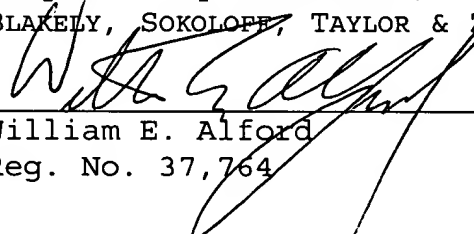
This is in response to the Notice of Non-Compliant Amendment mailed on 08/26/2003.

In the Notice of Non-Compliant Amendment, it was noted that a complete listing of all the claims was not presented in the preliminary amendment filed on 08/11/2003. In particular, a portion of withdrawn claim 48 was not presented and withdrawn claim 49 in its entirety was not presented due to an inadvertent error.

In response, Applicant respectfully resubmits herein the entire "Amendments to the claims" section of the prior document with a complete listing of all claims 1-55 in ascending numerical order including claims 48-49 in their entirety.

Respectfully submitted,
BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP

Dated: September 5, 2003

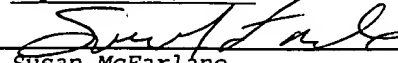


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